



PRODUCT DATA SHEET



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Datasheet



Resources



Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:

– IEC 61000-4-2 (ESD) immunity test

Air discharge: $\pm 15\text{kV}$

Contact discharge: $\pm 8\text{kV}$

– IEC61000-4-4 (EFT) 40A (5/50ns)

– IEC61000-4-5 (Lightning) 5A (8/20 μs)

RoHS Compliant

Applications

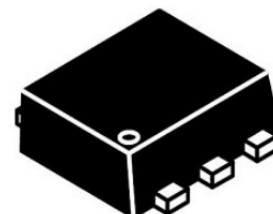
- Ethernet Interface
- Switchin Systems
- Access Equipment
- Central Of fice Equipment
- Customer Premise Equipment
- Microcontroller Input Protection

Mechanical Characteristics

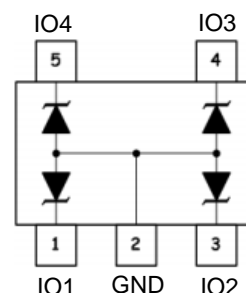
- Package: SOT-553
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7inch

Absolute Maximum Ratings (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P _{pp}	60	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 15	Kv
ESD per IEC 61000-4-2 (Contact)		± 8	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STJ}	-55 to +150	°C



SOT-553



Electrical Characteristics (TA=25°C unless otherwise specified)

Part Number	V _{RWM} (V)	V _{BR} (V)	I _T (mA)	V _C @1A	V _C		I _R μA (Max)	C (Pf) (Typ.)
					(Max)	(@A)		
RLST553A034V	5	6	1	9.8	12	5	0.5	0.7

Characteristic Curves

Fig1. 8/20μs Pulse Waveform

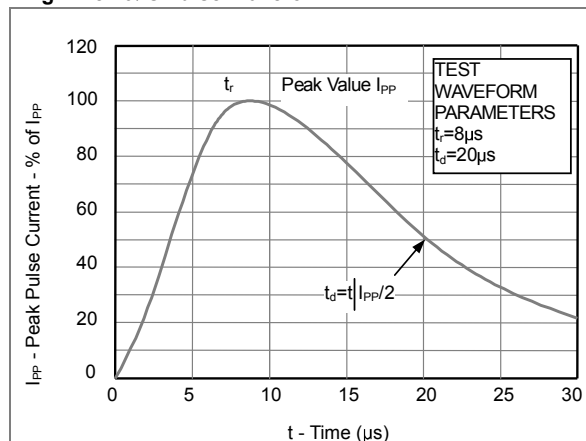


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

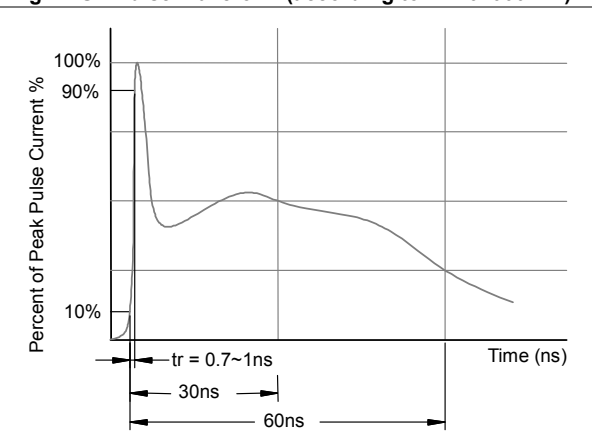
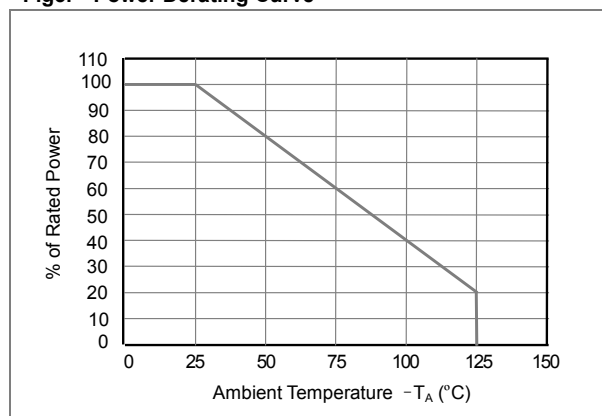
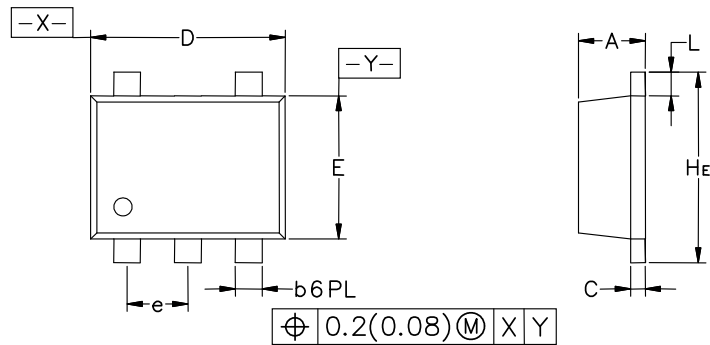
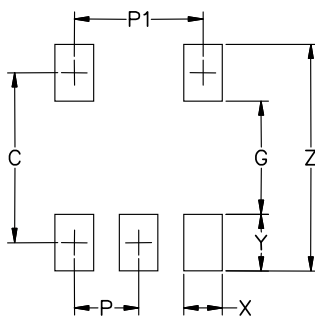


Fig3. Power Derating Curve



SOT-553 Package Outline & Dimensions


Symbol	Inches			Millimeters		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.020	0.021	0.023	0.50	0.55	0.60
b	0.007	0.009	0.011	0.17	0.22	0.27
C	0.003	0.005	0.007	0.08	0.12	0.18
D	0.059	0.062	0.066	1.50	1.60	1.70
E	0.043	0.047	0.051	1.10	1.20	1.30
e	0.02 BSC			0.5 BSC		
L	0.004	0.008	0.012	0.10	0.20	0.30
H_E	0.059	0.062	0.067	1.50	1.60	1.70

Soldering Footprint


Symbol	Inches	Millimeters
C	0.0531	1.35
G	0.0354	0.90
P	0.0197	0.50
P1	0.0394	1.0
X	0.0118	0.30
Y	0.0177	0.45
Z	0.0709	1.80

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